

MATERIAL DECLARATION SHEET



Material Number	CD1206-B Serial			
Product Line	Semiconductor Products			
Compliance Date	2004/08/02			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	6	Continuous filament glass fibers	65997-17-3	43	21.500	50.000
				Copper foil	7440-50-8	14	7.000	
				Non-Hazardous cured resin	Proprietary	43	21.500	
2	Epoxy	Plastic	4.804	Silicon Dioxide	7631-86-9	55	22.018	40.033
				P-F-R resin	9003-36-5	45	18.015	
3	Solder Cream	Metal	0.076	Lead*	7439-92-1	88	0.557	0.633
				Tin	7440-31-5	10	0.063	
				Silver	7440-22-4	2	0.013	
4	Dice	Others	0.88	Silicon	7440-21-3	90.46	6.634	7.334
				Silver	7440-22-4	8.5	0.623	
				Nickel	7440-02-0	0.67	0.049	
				Titanium	7440-32-6	0.27	0.02	
				Arsenic	7440-38-2	0.09	0.007	
5	Terminal Plating	Metal	0.24	Tin	7440-31-5	>99.9	2.000	2.000
				Total weight	12			

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This Document was updated on: 2015/04/29

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. *Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead) ;